



March 1997
Revised March 1999

74VHCT244A

Octal Buffer/Line Driver with 3-STATE Outputs

General Description

The VHCT244A is an advanced high speed CMOS octal bus transceiver fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. The VHCT244A is a non-inverting 3-STATE buffer having two active-LOW output enables. This device is designed to be used as 3-STATE memory address drivers, clock drivers, and bus oriented transmitter/receivers.

Protection circuits ensure that 0V to 7V can be applied to the input and output (Note 1) pins without regard to the supply voltage. These circuits prevent device destruction

due to mismatched supply and input/output voltages. This device can be used to interface 5V to 3V systems and two supply systems such as battery back up.

Note 1: Outputs in OFF-State

Features

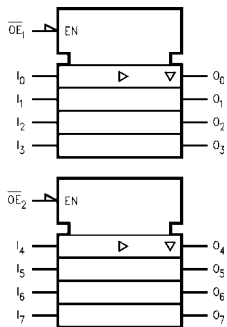
- High Speed: $t_{PD} = 5.9$ ns (typ) at $V_{CC} = 5V$
- Power down protection is provided on inputs and outputs
- Low power dissipation: $I_{CC} = 4$ μA (max) @ $T_A = 25^{\circ}C$
- Pin and function compatible with 74HCT244

Ordering Code:

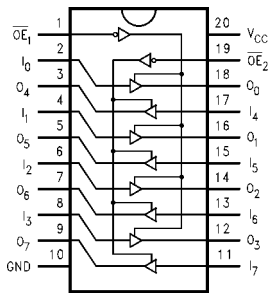
Order Number	Package Number	Package Description
74VHCT244AM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74VHCT244ASJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHCT244AMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74VHCT244AN	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs
I_0-I_7	Inputs
O_0-O_7	3-STATE Outputs

74VHCT244A Octal Buffer/Line Driver with 3-STATE Outputs

74VHCT244A

Truth Tables

Inputs		Outputs (Pins 12, 14, 16, 18)
\overline{OE}_1	I_n	
L	L	L
L	H	H
H	X	Z

Inputs		Outputs (Pins 3, 5, 7, 9)
\overline{OE}_2	I_n	
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
I = Immaterial
Z = High Impedance

74VHCT244A

Noise Characteristics

Symbol	Parameter	V _{CC} (V)	T _A = 25°C		Units	Conditions
			Typ	Limits		
V _{OLP} (Note 7)	Quiet Output Maximum Dynamic V _{OL}	5.0	0.9	1.1	V	C _L = 50 pF
V _{OLV} (Note 7)	Quiet Output Minimum Dynamic V _{OL}	5.0	-0.9	-1.1	V	C _L = 50 pF
V _{IHD} (Note 7)	Minimum HIGH Level Dynamic Input Voltage	5.0		2.0	V	C _L = 50 pF
V _{ILD} (Note 7)	Maximum LOW Level Dynamic Input Voltage	5.0		0.8	V	C _L = 50 pF

Note 7: Parameter guaranteed by design.

AC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	T _A = 25°C			T _A = -40°C to +85°C		Units	Conditions	
			Min	Typ	Max	Min	Max			
t _{PLH}	Propagation Delay Time	5.0 ± 0.5		5.4	7.4	1.0	8.5	ns		C _L = 15 pF
t _{PHL}				5.9	8.4	1.0	9.5			C _L = 50 pF
t _{PZL}	3-STATE Output Enable Time	5.0 ± 0.5		7.7	10.4	1.0	12.5	ns	R _L = 1 kΩ	C _L = 15 pF
t _{PZH}				8.2	11.4	1.0	13.5			C _L = 50 pF
t _{PLZ}	3-STATE Output Disable Time	5.0 ± 0.5		8.8	11.4	1.0	13.0	ns	R _L = 1 kΩ	C _L = 50 pF
t _{OSLH}	Output to Output Skew	5.0 ± 0.5			1.0		1.0	ns	(Note 8)	
t _{OSHL}										
C _{IN}	Input Capacitance			4	10		10	pF	V _{CC} = Open	
C _{OUT}	Output Capacitance			9				pF	V _{CC} = 5.0V	
C _{PD}	Power Dissipation Capacitance			18				pF	(Note 9)	

Note 8: Parameter guaranteed by design. t_{OSLH} = |t_{PLH max} - t_{PLH min}|; t_{OSHL} = |t_{PHL max} - t_{PHL min}|

Note 9: C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC (opr.)} = C_{PD} * V_{CC} * f_{IN} + I_{CC/8} (per F/F). The total C_{PD} when n pcs. of the Octal D Flip-Flop operates can be calculated by the equation: C_{PD (total)} = 20 + 12n.

The image contains three mechanical drawings of the M20B package:

- Top View:** Shows a rectangular package with 20 pins (11 on top, 10 on bottom). Dimensions include a width of $0.496 - 0.512$ (12.598 - 13.005) and a height of $0.394 - 0.419$ (10.008 - 10.643). A 30° TYP angle is shown for the bottom pins. Lead No. 1 is identified.
- Side View:** Shows the package profile with a maximum lead tip height of $0.010 - 0.029$ (0.254 - 0.737) at a 45° angle. The body width is $0.291 - 0.299$ (7.391 - 7.595). Lead tips are 0.004 (0.102) high, and all lead tips are 8° MAX TYP.
- Cross-sectional View:** Shows the internal structure with dimensions for the body ($0.093 - 0.104$ (2.362 - 2.642)), lead height (0.014 (0.356)), body width (0.058 (1.270) TYP), and a bottom layer (0.008 TYP (0.203)). The seating plane is indicated with a height of $0.004 - 0.012$ (0.102 - 0.305). Other dimensions include $0.016 - 0.050$ (0.406 - 1.270) TYP ALL LEADS and $0.014 - 0.020$ TYP (0.356 - 0.508).

Diagram of a 20-pin DIP package. The package is shown with pins numbered 1 through 20. The dimensions are given in inches and millimeters:

- Pin spacing: $0.295-0.319$ (7.5-8.1)
- Body width: $0.205-0.213$ (5.2-5.4)

Technical drawing of a 12-pin connector showing front and side views with dimensions in inches and millimeters.

Front View Dimensions:

- Overall length: $0.492-0.500$ (12.5-12.7)
- Pin pitch: 0.050 (1.27) TYP
- Pin height: $0.067-0.083$ (1.7-2.1)
- Pin diameter: $0.006-0.010$ (0.15-0.25) TYP
- Seating Plane: Indicated by a dashed line and arrow.
- Pin diameter tolerance: 0.006 (0.15)
- Pin diameter tolerance: $0.014-0.020$ (0.35-0.50) TYP
- Pin diameter tolerance: $0.000-0.010$ (0-0.25)
- Pin diameter tolerance: 0.071 (1.8)

Side View Dimensions:

- Overall height: $0.006-0.010$ (0.15-0.25) TYP
- Pin diameter: 0.049 (1.25) TYP
- Pin diameter tolerance: $0.016-0.031$ (0.4-0.8) TYP
- Pin diameter tolerance: $0.006-0.010$ (0.15-0.25) TYP
- Pin diameter tolerance: 0.071 (1.8)

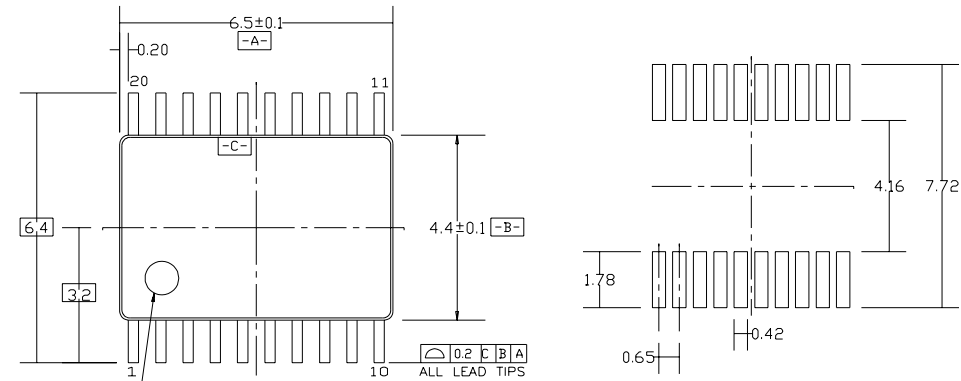
Notes:

- 0°-8° TYP

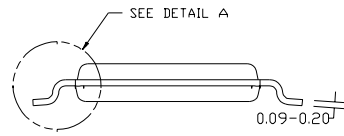
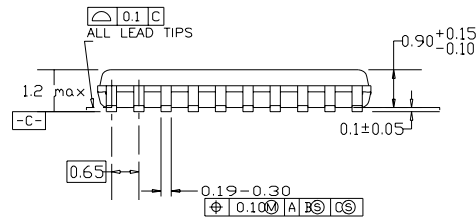
M202 (REV B)

74VHCT244A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



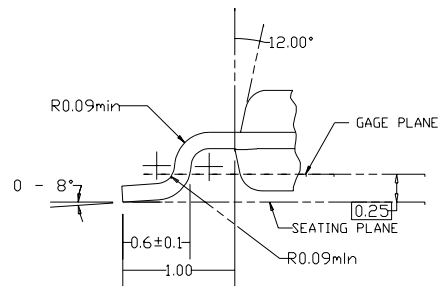
LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS

NOTES:

- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.



DETAIL A

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20**

